

05-27-2004



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17302 U.S. PTO

10/850201



051904

1. Name of Party(ies) conveying party(ies)

CHUN-WEN CHENG
CHIA-WEN LIANG
RICHARD LEE
VINCENT HSUEH

5.19.04

2. Names and address of party(ies) receiving an interest:

Name: UNITED MICROELECTRONICS CORP.

Internal Address:

Additional Name(s) of conveying party(ies) attached? ☐ Yes ☒ No05/25/2004 HMARZ11 00000031 10850201
03 FC:8021

40.00

Street Address: NO. 3, LI-HSIN RD. II, SCIENCE-BASED
INDUSTRIAL PARKCity: HSINCHU State: Zip:
TAIWAN, R.O.C.Additional name(s) & address(es) attached? ☐ Yes ☒ No

3. Nature of conveyance:

☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Other

Execution Date: MAY 6, 2004

4. Application number(s) or patent number(s): N / A

10850201

If this document is being filed together with a new application, the execution date of the application is:

MAY 18, 2004

A. Patent Application No.(s)

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☒ No5. Name and Address of party to whom correspondence
concerning document should be mailed:

Name: CHARLES C.H. WU

Internal Address:

Street Address: 7700 IRVINE CENTER DRIVE, SUITE 710

City: IRVINE State: CA Zip: 92618-3043

6. Total Number of applications and
registrations involved: [1]7. Total fee (37 CFR 2.6(b)(6)) [\$40.00]
☒ Enclosed
☐ Authorized to be charged to deposit account

8. Deposit account number:

(Attach duplicate copy of this page if paying by deposit account)

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9. Statement and signature.

To the best of my knowledge and belief, the forgoing information is true and correct and any attached copy is a true copy of the original document.

CHARLES C.H. WU

Name of Person Signing

Signature

MAY 18, 2004

Date

Total number of pages including cover sheet, attachments, and document: [4]

Mail documents to be recorded with required cover sheet information to:
Commissioner of Patents and Trademarks, Box Assignments

ASSIGNMENT

WHEREAS,

- | | |
|-------------------|-------------------|
| 1. Chun-Wen Cheng | 2. Chia-Wen Liang |
| 3. Richard Lee | 4. Vincent Hsueh |

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: **FUSE STRUCTURE FOR A SEMICONDUCTOR DEVICE**

[] Filed: Serial No.

[x] Executed concurrently with the execution of this instrument

WHEREAS, United Microelectronics Corp.
of No. 3, Li-Hsin Rd. II, Science-Based Industrial Park, Hsinchu, Taiwan, R.O.C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

-1-

CERTIF. OF EXPRESS MAILING (37 CFR 1.10)
 "Exp. Mail" label no.: EL 741138422 US
 Date of Deposit: MAY 18, 2004
 I hereby certify that this paper or fee is being deposited with
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 CFR 1.10 on the date indicated above and is addressed to
MAIL STOP PATENT APP. C&U. FOR PATENTS
P.O. BOX 1450, ALEXANDRIA, VA 22313-1450
MARY KIM

PATENT
REEL: 015363 FRAME: 0261

ASSIGNMENT CONTINUED

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Chun-Wen Cheng

Signature:

May 06, 2004

Date:

Sole or First Joint Inventor: Chun-Wen Cheng

Chia Wen Liang

Signature:

May 06, 2004

Date:

Second Joint Inventor (if any): Chia-Wen Liang

Richard Lee

Signature:

May 06, 2004

Date:

Third Joint Inventor (if any): Richard Lee

許勝之 Vincent Hsueh

Signature:

May 06, 2004

Date:

Fourth Joint Inventor (if any): Vincent Hsueh

許勝之